

6A A

7

d d

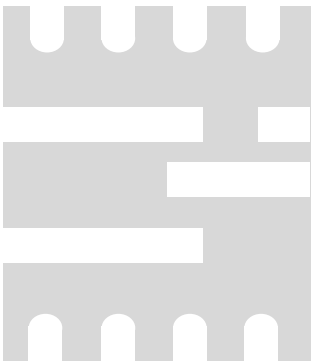
?

?

A D

A ? ? ?

C ? ?

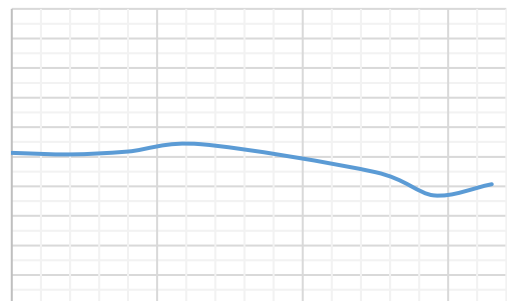
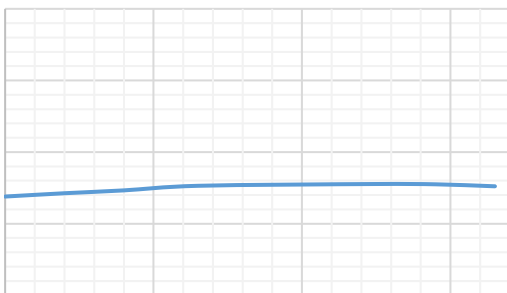
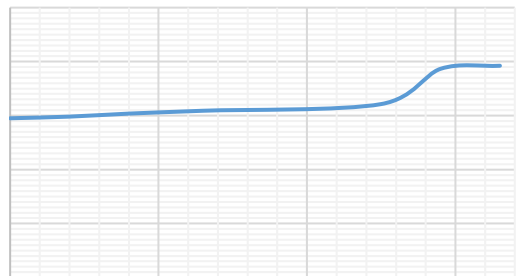
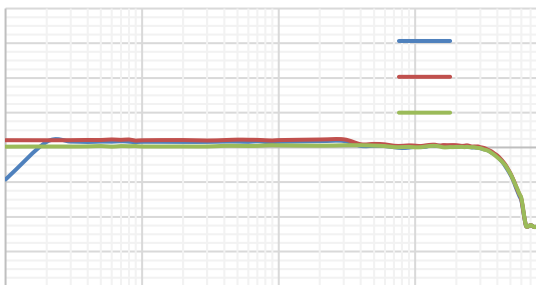
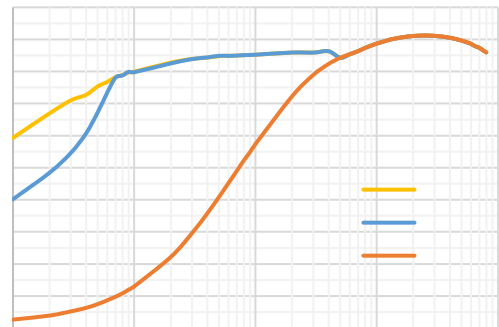
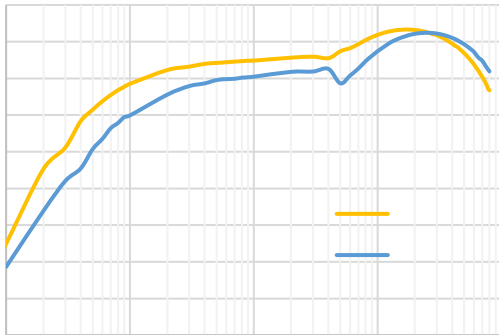


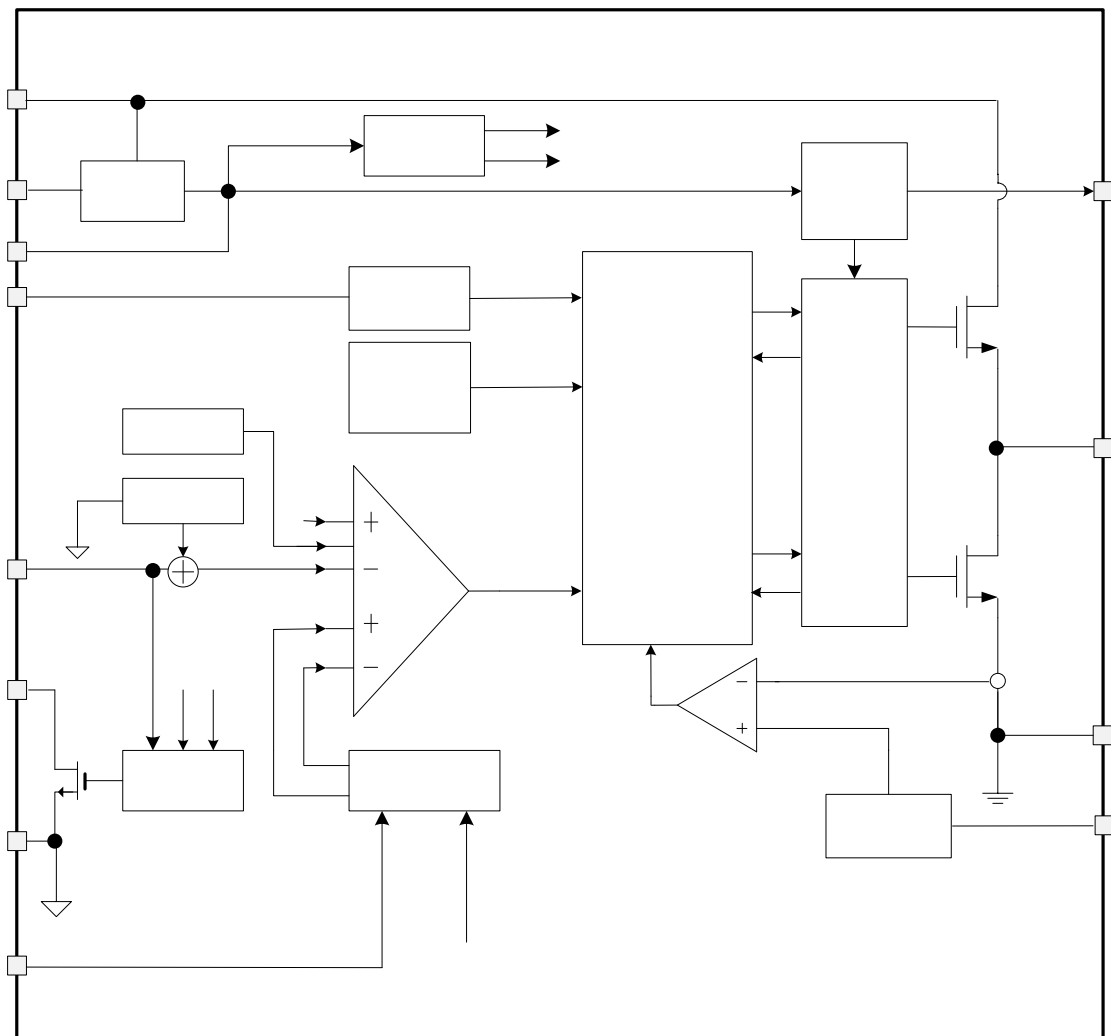
	0	

D

?

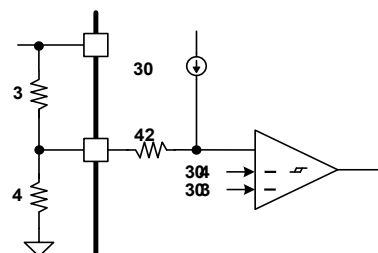
?





?

Ω



40

—

—

[Redacted]

[Redacted]

5

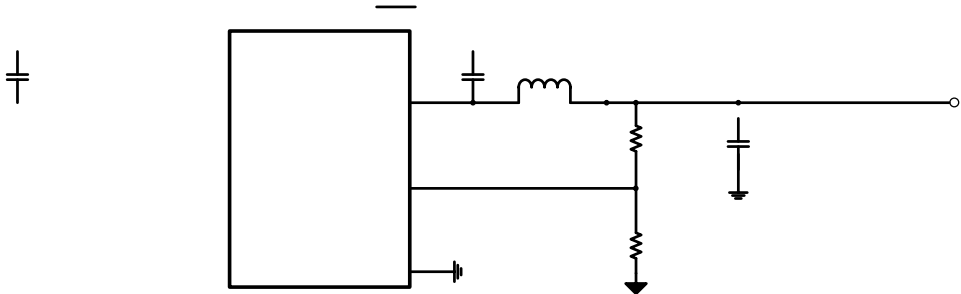
		9		

[Redacted]

—

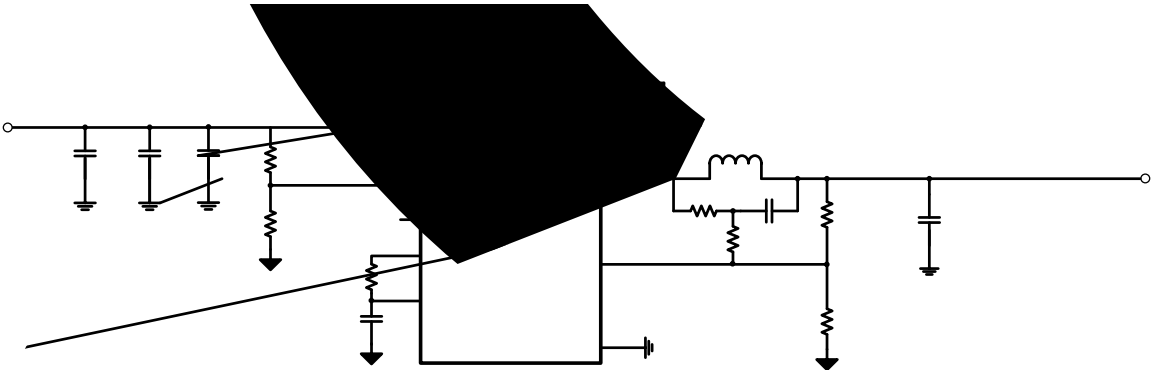
—

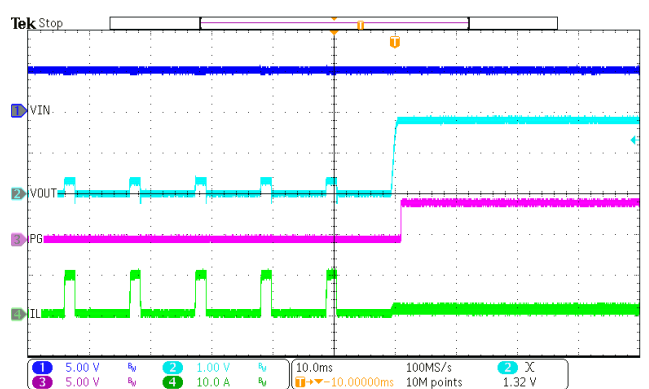
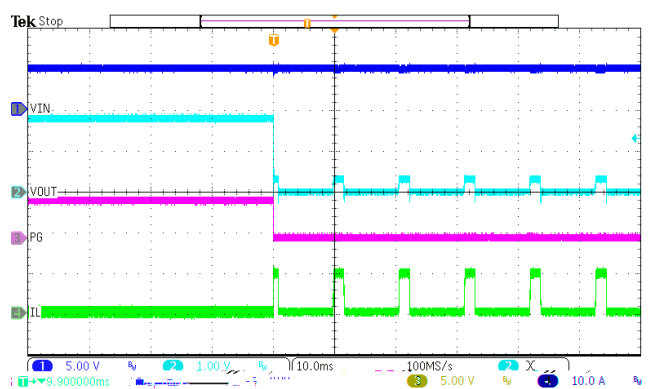
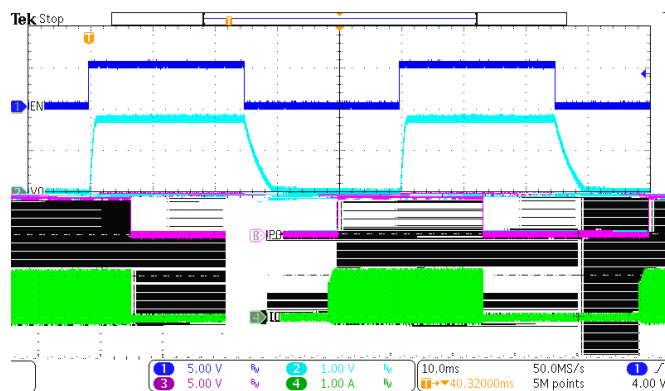
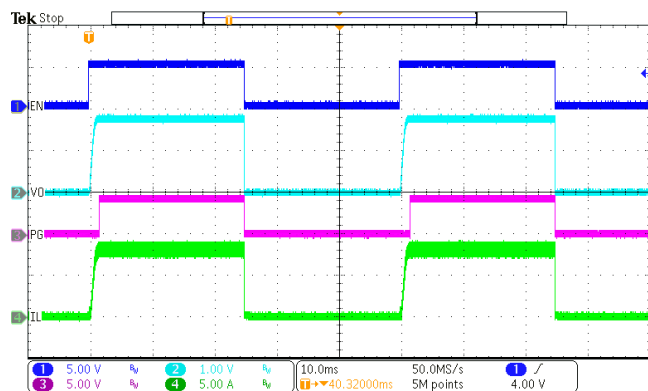
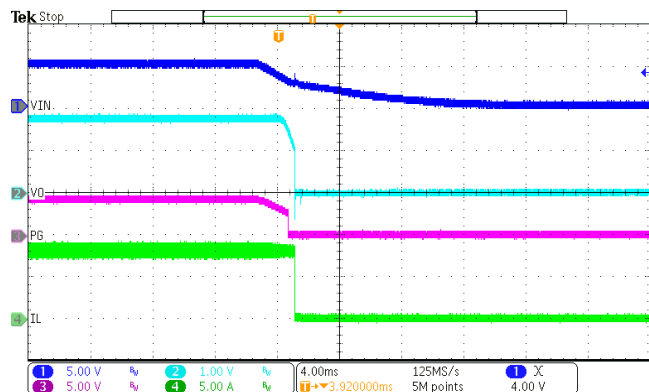
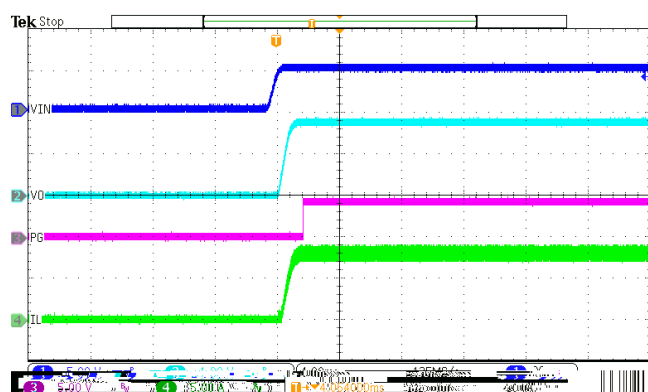
2

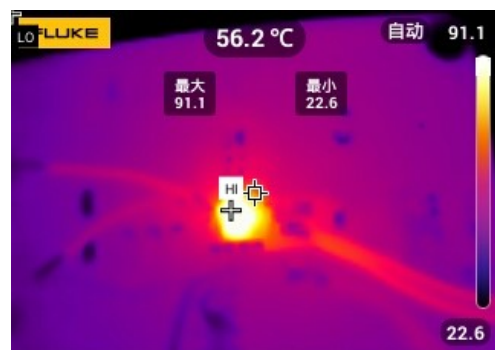
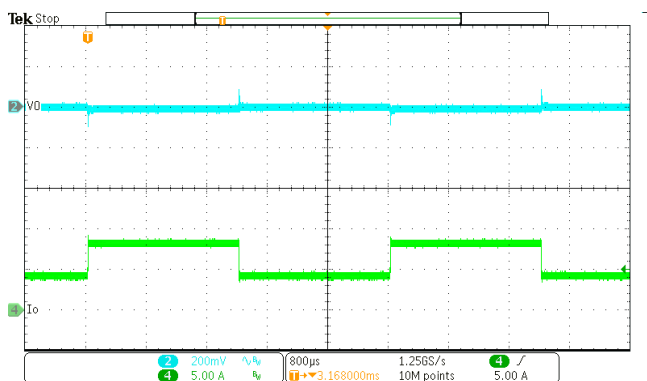
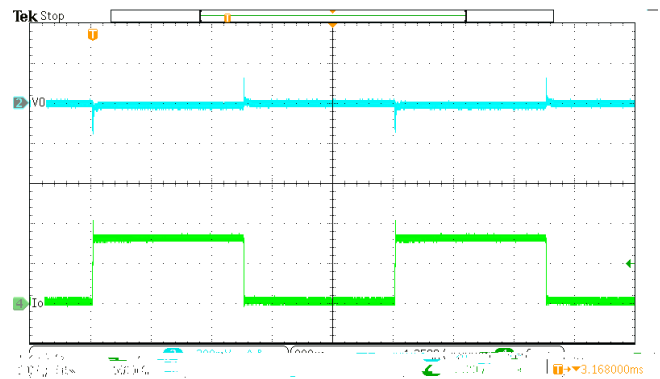
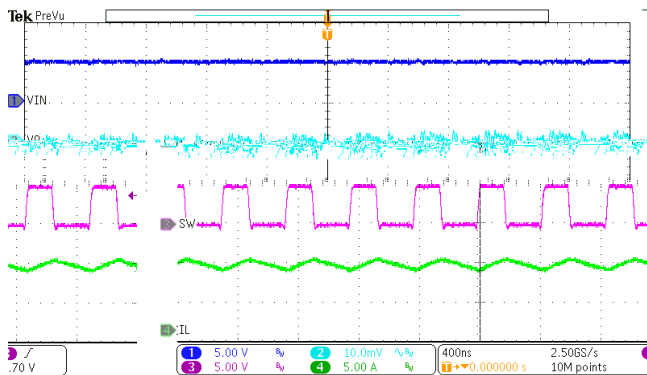
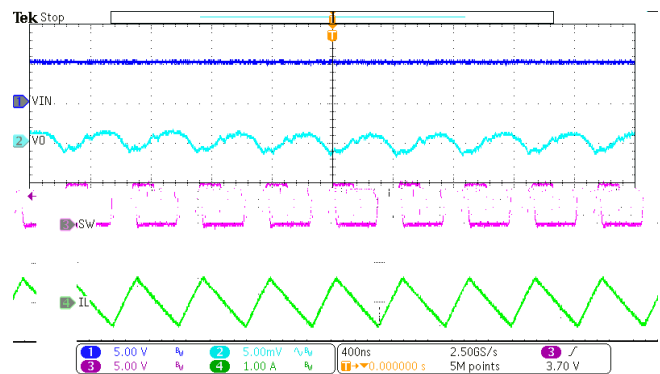
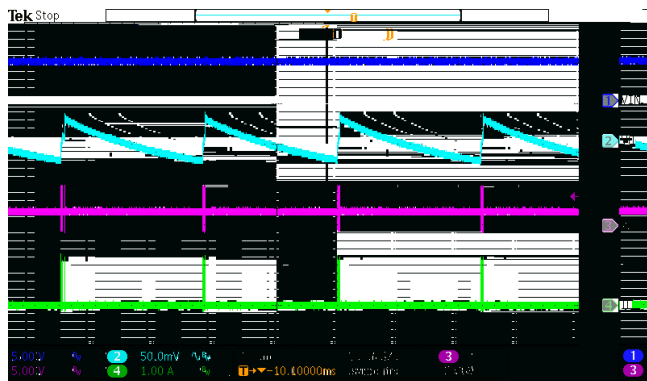




2







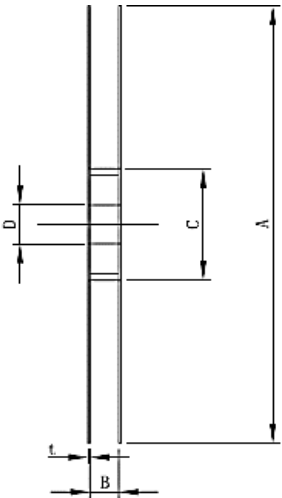
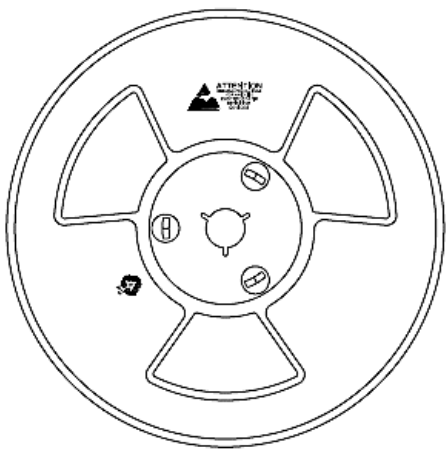
The bottom layer is a large ground plane connected to the ground plane on top layer by vias it is recommended 8mil diameter drill holes of thermal vias, but a smaller via offers less risk of solder volume loss. On applications where solder volume loss through the vias is of concern, plugging or tenting can be used to achieve a repeatable process.

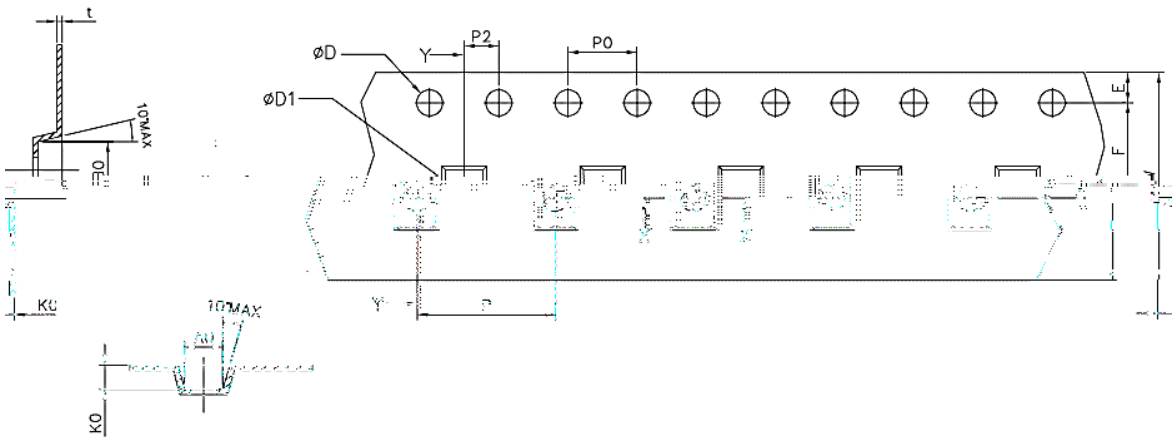


3			0
4			
5	0		
6		0	
7		0	
8	4420		0

2

2





4			
3			
2			
2			
2			
2			